

L Number	Hits	Search Text	DB	Time stamp
3	24633	defect\$ and mask\$ and etch\$ and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:53
4	2668	(defect\$ and mask\$ and etch\$ and semiconductor) and emitter	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:53
5	165	((defect\$ and mask\$ and etch\$ and semiconductor) and emitter) and (cone or conic)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:53
6	11090	(defect\$ and mask\$ and etch\$ and semiconductor) and implant\$	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:54
7	592	((defect\$ and mask\$ and etch\$ and semiconductor) and implant\$) and precipitat\$	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:54
8	71	(((defect\$ and mask\$ and etch\$ and semiconductor) and implant\$) and precipitat\$) and tip	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:56
9	1738	((defect\$ and mask\$ and etch\$ and semiconductor) and implant\$) and emitter	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:58
10	64	(((defect\$ and mask\$ and etch\$ and semiconductor) and implant\$) and emitter) and (cone or conic)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:58
11	5664	(protuberance or cone or conic) and emitter	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:59
12	1550	((protuberance or cone or conic) and emitter) and etch\$	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 11:59
13	367	(((protuberance or cone or conic) and emitter) and etch\$) and (defect\$ or dislocation or vacancy)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 12:00
14	239	(((protuberance or cone or conic) and emitter) and etch\$) and (defect\$ or dislocation or vacancy)) and mask\$	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/13 12:00

15	239	(((((protuberance or cone or conic) and emitter) and etch\$) and (defect\$ or dislocation or vacancy)) and mask\$) and etch\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 12:01
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